

客户 CUSTOMER:

日期 DATE:

Preliminary

纳入仕様书
SPECIFICATION

产品名称 PRODUCT NAME: Diplexer

贵司料号 YOUR PART NO.:

敝司料号 OUR PART NO.: MDPX21M2124P69-D37X

版本号 VERSION.: V1.1

接受 RECEPTION

THE SPECIFICATION HAS BEEN ACCEPTED.

该纳入仕様书已被我司接受

日期:
DATE:公司:
COMPANY:批准
CFMD审核
CHKD接收
RCVD

本纳入仕様书共 12 页

MANUFACTURING NAME

深圳市麦捷微电子科技股份有限公司

SHENZHEN MICROGATE TECHNOLOGY CO., LTD

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梁启新	付迎华	曾艳峰

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纳入仕様书改定履历 MODIFY HISTORY OF SPECIFICATION

Ver..	DATE	CONTENT	APPROVED
1.0	2019.08.13	初稿 Constitute	梁启新
1.1	2019.11.11	分频段给出插入损耗 Insertion loss given in sub Band	梁启新

目录 CATALOG

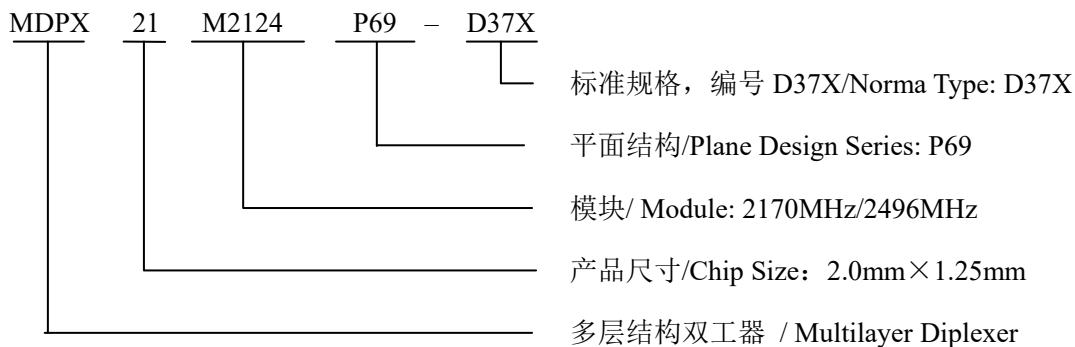
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1 适用范围 Scope

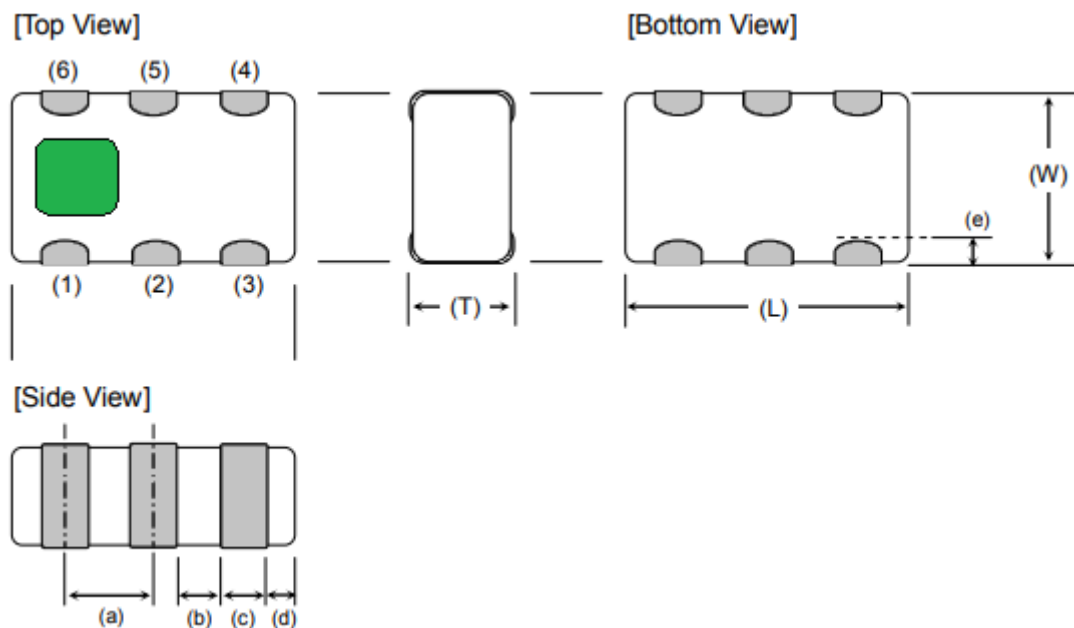
麦捷 Diplexer (MDPX 系列) 产品设计用于 5G、LTE、WIFI、Bluetooth、PDA 和无绳电话机中, 具有低的插入损耗、高的衰减和小体积 SMD 片式设计, 能减少复杂的调校工作, 可以简化电路设计。

“Microgate” Microwave Diplexer series are designed to be used in 5G、LTE、WIFI、Bluetooth、PDA & Cordless phones with low insertion loss and high attenuation as well as small size SMD chip design, which can simplify your complex tuning and circuit design.

2 品名构成 Product Identification



3 形状、尺寸和材料 Appearance, Dimensions and Material



Dimension (mm)

L	W	T	a	b	c	d	e
2.00±0.15	1.25±0.15	0.9±0.10	0.65±0.15	0.35±0.15	0.30±0.15	0.20±0.15	0.20±0.15

PIN Assignment

(1)	(2)	(3)	(4)	(5)	(6)
GND	Common	GND	High Band	GND	Low Band

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Part Name 名称	Structure and Material 结构及材料
Resonator 谐振体	Dielectric Material LTCC 介质材料
In/Output Terminals 输入/输出	Ag 银/Ni 镍/Sn 锡
Ground Base 接地面	Ag 银/Ni 镍/Sn 锡

4 测试条件 Testing Conditions

除非另有规定，否则在以下条件下测试 <Unless otherwise specified>

温度 Temperature : Ordinary Temperature (-40 to +85℃)

湿度 Humidity : Ordinary Humidity (25 to 85% RH)

大气压强 Atmospheric Pressure : 86 to 106 kPa

当对测量结果有疑问时<In case of doubt>

温度 Temperature : 20±2℃

湿度 Humidity : 60 to 75% RH

大气压强 Atmospheric Pressure : 86 to 106 kPa

5 电气性能 Electrical Characteristics

操作温度范围 Operating Temperature Range : -40 to +85℃

保存温度范围 Storage Temperature Range : -40 to +85℃

LB:Low Band Port HB: High Band Port ANT: Common Port

Low Band Port

No. (序号)	Item (项目)		Unit (单位)	Specifications (特性)			Notes (备注)
				下限值 Min	典型值 Typ	上限值 Max	
1	频率范围	Frequency Range	MHz	698	/	2170	
2	插入损耗 Insertion Loss	698~960MHz	dB	/		0.5	-30~85℃
		1420~1610MHz				0.6	-30~85℃
		1710~1920MHz				0.8	-30~85℃
		1920~1990MHz				1	-30~85℃
		1990~2170MHz				1.65	-30~85℃
		698~960MHz				0.4	RT(25℃)
		1420~1610MHz				0.5	RT(25℃)
		1710~1920MHz				0.65	RT(25℃)
		1920~1990MHz				0.8	RT(25℃)
		1990~2170MHz				1.4	RT(25℃)

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3	驻波比 VSWR (LB/ANT)	698~2170MHz		/	/	2	-30~85°C
4	带外抑制度 Rejection	2402 – 2482MHz	dB	15	20	/	
		2496 – 2690 MHz		15	20	/	
		4900 – 5900MHz		30	35	/	
5	Port impedance 端口阻抗		Ω	50			

High Band Port

No. (序号)	Item (项目)		Unit (单位)	Specifications (特性)			Notes (备注)
				下限值 Min	典型值 Typ	上限值 Max	
1	频率范围	Frequency Range	MHz	2496	/	2690	
2	插入损耗 Insertion Loss	2496~2515MHz	dB	/		1.55	-30~85°C
		2515~2675MHz				1.4	-30~85°C
		2675~2690MHz				1.1	-30~85°C
		2496~2515MHz				1.35	RT(25°C)
		2515~2675MHz				1.2	RT(25°C)
		2675~2690MHz				0.9	RT(25°C)
3	驻波比 VSWR (HB/ANT)	2496~2690MHz		/	/	2	
4	带外抑制度 Rejection	698 – 960MHz	dB	20	25	/	
		2110 – 2170 MHz		15	20/	/	
5	Port impedance 端口阻抗		Ω	50			

Low Band to High band

No. (序号)	Item (项目)		Unit (单位)	Specifications (特性)			Notes (备注)
				下限值 Min	典型值 Typ	上限值 Max	
1	隔离度 Isoation	698 – 1980 MHz	dB	18	25	/	RX
		2110 – 2170 MHz		15	20	/	TX
		2496 – 2690MHz		18	25	/	
2	Port impedance 端口阻抗		Ω	50			

Quality and stability

No. (序号)	Item (项目)	Unit (单位)	Specifications (特性)			Notes (备注)
			下限值 Min	典型值 Typ	上限值 Max	
1	ESD(HBM)	V	>100V			
	ESD(CDM)	V	>100V			
	Humidity Grade		MLS1			
	Storage cycle(package)	year	>1			
2	Power Capacity 功率容量	dBm	35			

6 焊接条件 Recommended Soldering Conditions

1、焊剂 Flux, Solder

① 使用松香助焊剂，禁止使用卤化物含量超过 0.2wt% 的强酸性助焊剂。

Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).

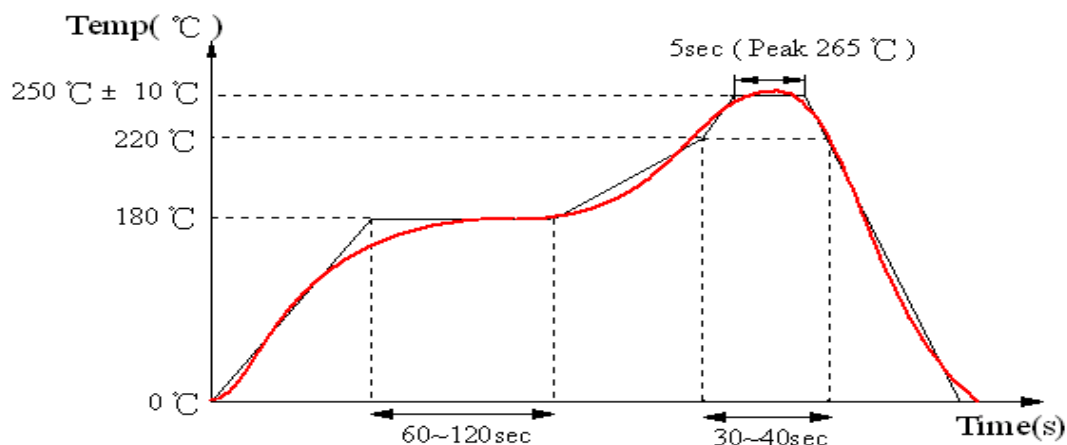
② 使用纯锡焊料 Use Sn solder.

2、回流焊条件 Reflow soldering conditions

● 预热时，产品表温与焊料温度的温差最大不允许超出 150℃，焊接完后冷却时，产品表温与溶剂温度之间的温差最大不允许超出 100℃。预热不足有可能引发产品表面裂纹，导致产品品质下降。

Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150℃ max. Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100℃ max. Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.

● 标准回流焊曲线 Standard soldering profile.



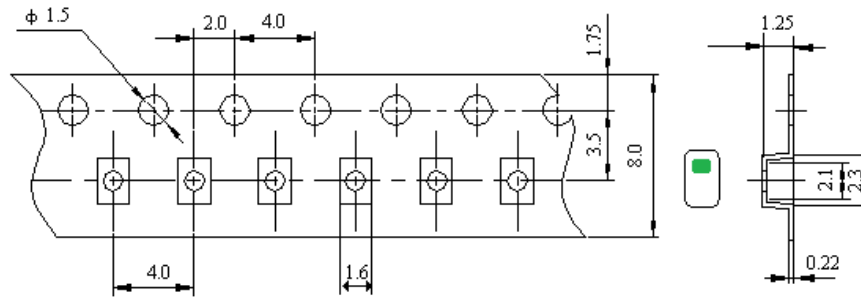
3、手工返工 Reworking with soldering iron

当使用电烙铁进行手工焊接时，以下条件必须严格遵守 The following conditions must be strictly followed when using a soldering iron.

预热 Pre-heating	150℃, 1 minute
尖端温度 Tip temperature	350℃ max
输出功率 Soldering iron output	80w max
电烙铁头尖端尺寸 End of soldering iron	φ3mm max
焊接时间 Soldering time	3 seconds max

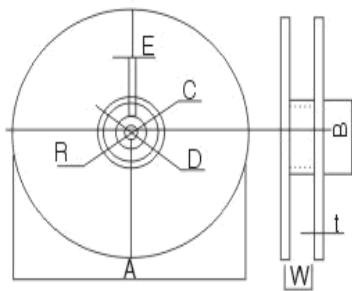
7 包装 Packaging

①编带尺寸 Dimensions of Tape:



②带轮尺寸 Dimensions of Reel

Unit: mm



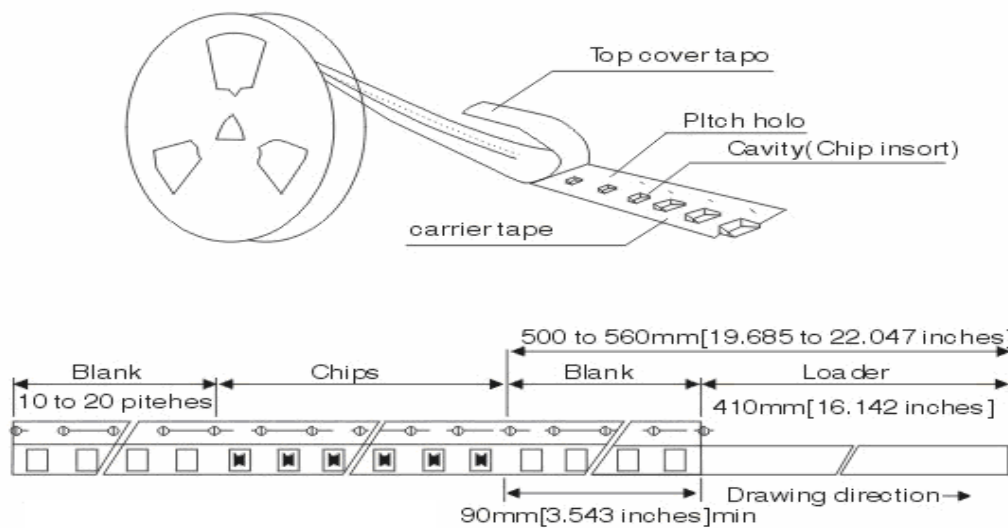
Reel material: PS (Polystyrene)

A	178±2
B	60±2
C	13.0±0.5
D	21.0±0.8
E	2.0±0.5
W	8.5±1.0
t	1.2±0.2
R	1.0±0.25

③带抗拉强度 Pulling strength of tapes:

载带 Carrier tape	10N or more (1kgf or more)
上盖带 Cover tape	5N or more (1kgf or more)

④编带简图及拉伸方向 Taping figure and drawing direction:



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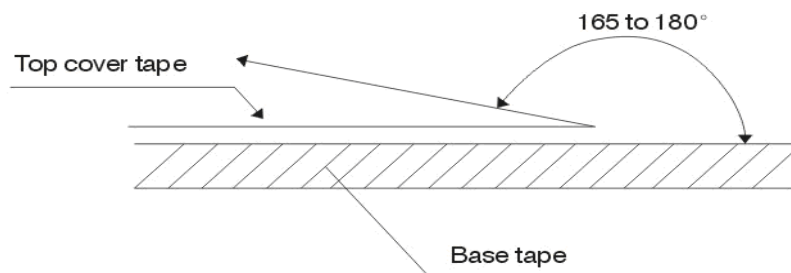
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⑤盖带的剥离强度 Peeling strength of cover tape:

盖带 Cover tape	0.3~0.7N (30gf~70gf)
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测试条件

- 1) 剥离角度 peel angle: 165°~180° vs. carrier tape.
- 2) 剥离速度 peel speed: 300mm/min±10%.

⑥ 包装数量 Packaging quantities: 3000 PCS / Reel

8 装箱清单及标志 Packing documents and marking

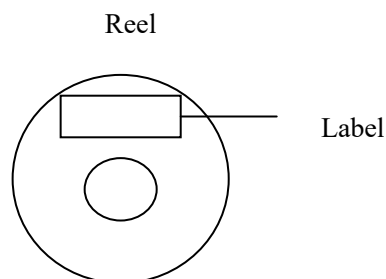
1. 包装文件 Packing documents

Packing includes the following:

- a. 装箱清单 Packing list.
- b. 合格证书 Certificate of compliance.

2. 盘上标记 Marking on reels:

- a 麦捷料号 MICROGATE Part No.
- b 生产批号 Lot number
- c 盘装数量 Quantity per reel
- d 检验员号 Inspector No.



以上内容必须在标签上注明.All above shall be shown on marking label

麦捷公司标签如下所示: MICROGATE marking label will be as following:

MICROGATE		
CUSTOMER:	P. O. NO	
CUSTOMER PART NO:	DATE CODE	LOT NO
MG PART NO:	QUANTITY	INSP. NO



MG PART NO

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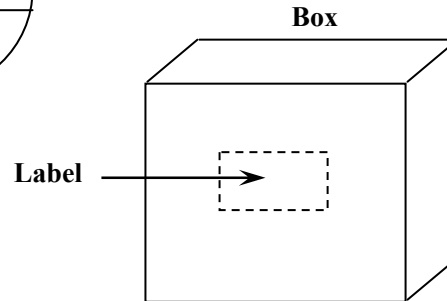
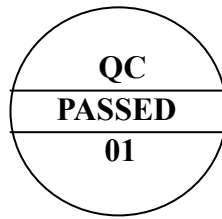
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检验合格后,检验员在标签上盖上合格章。合格章如下所示: The eligible reels will be pressed a mark onto the surface. The mark will be as following:



3. 内包装盒标记:Marking on inner box

- a. 型号 MICROGATE part No.
- b. 每盒数量 Quantity per box
- c. 包装日期 Date

以上内容必须在标签上注明 (标签见 8.2 所示)。Above shall be shown on marking label (The marking label is shown in item 8.2).

4. 外包装箱标记 Marking on outer case:

1) 制造商 Manufacturer: “MICROGATE” ①

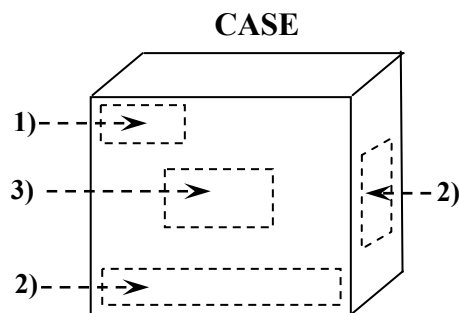
“中国深圳制造” “Made in Shenzhen CHINA”②

2) 发运标记 Ship marking:

“向上” “UP”, “小心轻放”“HAND CARE”, “防潮”“MOISTURE-PROOF”.

3) 包装标签包括以下内容 Packing label include the following:

- a. 型号 MICROGATE Part No
- b. 总数量 Total quantity per case
- c. 包装日期 Date;



以上内容必须在标签上注明。(参见 8.2 所示)

All above shall be shown on marking label.

(The marking label is shown in item 8.2)

9 保管 Storage

①. 保管期限 Storage period

距麦捷出厂检验时间 12 个月内，产品可以使用；检验时间可以通过包装外侧标记的检验号确认；若时间超出 12 个月，应检查焊接性能后方可使用。Products which inspected in MICROGATE over 12 months ago should be examined and used, which can be confirmed with inspection No. marked on the container. Solder ability should be checked if this period is exceeded.

②. 保存条件 Storage conditions

●存放货物的库房应满足以下条件 Products should be storage in the warehouse on the following conditions

温度 Temperature: 10~40℃

湿度 Humidity : 30~70% relative humidity

不允许温、湿度有极剧变化。No rapid change on temperature and humidity

●禁止将产品保管在腐蚀性物质中，例如硫磺、氯气或者酸，否则将引起端头氧化，导致降低焊接性。Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solder ability.

●为了避免受潮气、灰尘等物质的影响，产品应保管于货架上。Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.

●产品保管在库房中时，应避免热冲击，振动以及直接光照等等。Products should be storage in the warehouse without heat shock, vibration, and direct sunlight and so on.

●产品应密封包装 Products should be storage under the airtight packaged condition.